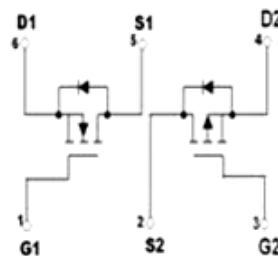
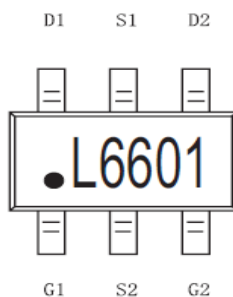
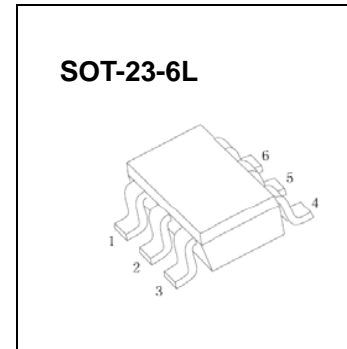


SOT-23-6L Plastic-Encapsulate MOSFETS

CJL6601 P-channel and N-channel Complementary MOSFETS

GENERAL DESCRIPTION

The CJL6601 uses advanced trench technology to provide excellent $R_{DS(on)}$ and low gate charge. The complementary MOSFETS form a high-speed power inverter and suitable for a multitude of applications.



Maximum Ratings ($T_A=25^\circ\text{C}$ unless otherwise noted)

Parameter	Symbol	Value		Unit
		N-channel	P-channel	
Drain-Source Voltage	V_{DS}	30	-30	V
Gate-Source Voltage	V_{GS}	± 12	± 12	V
Continuous Drain Current ⁽¹⁾	I_D	3.4	-2.3	A
Pulsed Drain Current ⁽²⁾	I_{DM}	30	-30	A
Power Dissipation	P_D	0.35	0.35	W
Thermal Resistance from Junction to Ambient ⁽¹⁾	$R_{\theta JA}$	357	357	$^\circ\text{C}/\text{W}$
Junction Temperature	T_J	150	150	$^\circ\text{C}$
Storage Temperature	T_{stg}	-55~+150	-55~+150	$^\circ\text{C}$

1. The value of $R_{\theta JA}$ is measured with the device mounted on 1in² FR-4 board with 2oz. Copper, in a still air environment with $T_A=25^\circ\text{C}$. The value in any given application depends on the user's specific board design. The current ratings is based on $t \leq 10\text{s}$ thermal resistance rating.

2. Repetitive rating, pulse with limited by junction temperature.

N-channel MOSFET Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = 250μA	30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = 24V, V _{GS} = 0V			1	μA
Gate-source leakage current (note1)	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Drain-source on-resistance (note1)	R _{DS(on)}	V _{GS} = 10V, I _D = 3A			60	mΩ
		V _{GS} = 4.5V, I _D = 3A			75	mΩ
		V _{GS} = 2.5V, I _D = 2A			115	mΩ
Forward transconductance (note1)	g _{FS}	V _{DS} = 5V, I _D = 3A	5			S
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250μA	0.6		1.4	V
Diode forward voltage (note1)	V _{SD}	I _S = 1A, V _{GS} = 0V			1	V
Dynamic characteristics (note2)						
Input capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = 15V, f = 1MHz		390		pF
Output capacitance	C _{oss}			54.5		pF
Reverse transfer capacitance	C _{rss}			41		pF
Gate resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		3		Ω
Switching Characteristics (note2)						
Turn-on delay time	t _{d(on)}	V _{GS} = 10V, V _{DS} = 15V, R _L = 5Ω, R _{GEN} = 6Ω		4		ns
Turn-on rise time	t _r			2		ns
Turn-off delay time	t _{d(off)}			22		ns
Turn-off fall time	t _f			3		ns

P-channel MOSFET Electrical Characteristics (T_A=25°C unless otherwise noted)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static characteristics						
Drain-source breakdown voltage	V _{(BR)DSS}	V _{GS} = 0V, I _D = -250μA	-30			V
Zero gate voltage drain current	I _{DSS}	V _{DS} = -24V, V _{GS} = 0V			-1	μA
Gate-source leakage current	I _{GSS}	V _{GS} = ±12V, V _{DS} = 0V			±100	nA
Drain-source on-resistance (note1)	R _{DS(on)}	V _{GS} = -10V, I _D = -2.3A			135	mΩ
		V _{GS} = -4.5V, I _D = -2A			185	mΩ
		V _{GS} = -2.5V, I _D = -1A			265	mΩ
Forward transconductance (note1)	g _{FS}	V _{DS} = -5V, I _D = -2.3A	5			S
Gate threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250μA	-0.6		-1.4	V
Diode forward voltage (note1)	V _{DS}	I _S = -1A, V _{GS} = 0V			-1	V
Dynamic characteristics (note2)						
Input capacitance	C _{iss}	V _{GS} = 0V, V _{DS} = -15V, f = 1MHz		409		pF
Output capacitance	C _{oss}			55		pF
Reverse transfer capacitance	C _{rss}			42		pF
Gate resistance	R _g	V _{GS} = 0V, V _{DS} = 0V, f = 1MHz		12		Ω
Switching Characteristics (note2)						
Turn-on delay time	t _{d(on)}	V _{GS} = -10V, V _{DS} = -15V, R _L = 6Ω, R _{GEN} = 6Ω		13		ns
Turn-on rise time	t _r			10		ns
Turn-off delay time	t _{d(off)}			28		ns
Turn-off fall time	t _f			13		ns

Notes : 1. Pulse Test : Pulse width ≤ 300μs, duty cycle ≤ 0.5%.

2. Guaranteed by design, not subject to production testing.